PCN# : P2BGA
Issue Date : Feb. 19, 2013

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : May. 20, 2013

Expected First Date Code of Changed Product :1311

Description of Change (From) :
Fairchild Semiconductor Maine solder bump

Description of Change (To) :
Fairchild Semiconductor Maine solder bump and the addition of Amkor Technology, site T5 Hsinchu, Taiwan solder bump

Reason for Change:

To further ensure critical supply chain continuity to our key customers, Fairchild is expanding the use of an existing and fully qualified source for alternate wafer level chip scale device processing. This change is planned to take effect immediately upon customer approval. Please contact your local Customer Quality Engineer immediately upon receipt of this notification if you require any additional data or samples. Timely approval of this PCN will help to protect your supply chain against any unforeseen supply disruptions.

Affected Product(s):

FAB3102UCX		

Qualification Plan	**Device**	**Package**	**Process**	**No. of Lots**
Q20120102	FSA2269UCX	UCBBU	TSMC CM.18G(3.3V), 3LM fab Amkor T5/T3 process/bump qualification	3

Test Description:	**Condition:**	**Standard :**	**Duration:**	**Results:**
Operation Life	110C, 4.3V	JESD22-A108	1000 hrs	0/231
Highly Accelerated Stress Test	130C, 85%RH, 4.3V	JESD22-A110	96 hrs	0/135
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	1000 Cycles	0/231